



SEMI International Standards Program Japan Packaging Committee Meeting

March 25, 2013, 15:00 – 17:00
SEMI Japan, Tokyo, Japan

AGENDA

1. Welcome and Call to Order

- 1.1. Self-Introduction
- 1.2. Agenda Review
- 1.3. SEMI Technical Award

2. Required Meeting Elements

- 2.1. Program Membership Requirement
- 2.2. Anti-Trust Reminder
- 2.3. Intellectual Property Reminder
- 2.4. International Effective Meeting Guidelines

3. Review and Approval of Previous Meeting Minutes

4. SEMI Staff Report

5. Liaison Reports

- 5.1. GCS Report (if any)
- 5.2. North America 3DS-IC Committee Report
- 5.3. Taiwan 3DS-IC Committee Report

6. Ballot Review

- 6.1. Doc.#4965C, NEW STANDARD: Mechanical Interface Specification for 450 mm Load Port for Tape Frame Cassettes in the Backend Process

7. Task Force Report

- 7.1. Electromagnetic Characterization Study Group (Kiyono-san)
- 7.2. Packages and Packaging Materials Eco-efficiency Task Force (Nakamura-san/ Suzuki-san)
- 7.3. Wafer Shipping Container for Assembly & Packaging Task Force (Nakamura-san/ Shimizu-san/ Yanagawa-san)
- 7.4. DFM Study Group (Anjo-san)
- 7.5. Japan 450mm Assembly & Test Die Preparation Task Force (Masuchi-san/ Kawai-san/ Tanaka-san/ Watanabe-san)
- 7.6. 3D-IC Study Group (Tsuruya-san)



8. Old Business

8.1. Previous Action Items

Action Item #	Assigned to	Details	Status
PKG111125-1	Sumio Masuchi	To draft a related document for Doc. 4814A (New Standard: Specification for Tape Frame Cassette for 450 mm Wafer)	
PKG120829-2	Committee Co-Chairs	To review the Committee Charter of Japan Packaging Committee	
PKG120829-3	All Task Force Leaders	To review the both TFOF (Charter, Scope and Members) and SNARFs (Rationale and Scope) which they themselves are involved	
PKG121206-1	Japan Assembly & Test Die Preparation Task Force	To submit Doc.#4965C for Cycle 1, 2013.	

9. New Business

10. Conclusion

10.1. Action Item Review

10.2. Next Japan Packaging Committee Meeting

10.3. Adjournment